TGP1200 Thermal Gap Filler Pad

BENEFITS AND FEATURES

- High thermal performance
- Ultra-high compressibility for low stress applications
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductor logics & memory

OVERVIEW

Honeywell TGP1200 Thermal Gap Filler Pads provide high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing. TGP1200 naturally tacky, and require no additional adhesive which could inhibit thermal performance. Products are available in thickness range from 0.5mm to 5.0mm.

STORAGE & USE

- Shelf life 12 months at 0-35°C, ⩽65% RH

Property	TGP1200	Test Method
Color	Blue	Visual
Thickness (mm) 1*	0.5-5.0	ASTM D374
Density(g/cm^3)	1.8	ASTM D792
Hardness (Shore00)	40	ASTM D2240
Thermal Conductivity (W/m·K)	1.2	ASTM D5470
Thermal Impedance (°C·in^2/W) (1mm@10psi, Typical Value)	1.19	ASTM D5470
Dielectric Constant@1MHz	5.5	ASTM D150
Volume Resistivity (ohm-cm)	1.0x 10^{13}	ASTM D257
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

1* Thickness range: 0.5-5.0mm with 0.25mm incremental
Thickness Tolerance: >=1.0mm, ±10%
0.5-1.0mm, ±0.1mm

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593

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